Amendments to the Claims

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Claim 1 (Canceled)

Claim 2 (Currently Amended): A semiconductor device comprising:

a die pad section having a surface and a back surface;

a first semiconductor chip having a surface on which a first electrode section is formed, and a back surface fixed to the surface of the die pad section;

a second semiconductor chip having a surface on which a second electrode section is formed, and a back surface fixed to the surface of the first semiconductor chip by an adhesive, wherein the adhesive is disposed on an entirety of the back surface of the second semiconductor chip;

lead terminal sections respectively electrically connected to the first and second electrode sections; and

a resin encapsulating body that seals the surface and the back surface of the die pad section, and the first and second semiconductor chips,

wherein an edge portion of the second semiconductor chip protrudes from an edge portion of the first semiconductor chip, an edge portion of the die pad section

protrudes from the edge portion of the first semiconductor chip, and the edge portion of the die pad section further protrudes from the edge portion of the second semiconductor chip.

Claim 3 (Previously Presented): A semiconductor device according to claim 2, wherein the surface of the first semiconductor chip has first and second sides opposite to each other,

the surface of the second semiconductor chip has third and fourth sides opposite to each other,

the surface of the die pad section has fifth and sixth sides opposite to each other,

the fourth side of the second semiconductor chip protrudes from the second side of the first semiconductor chip, and

the sixth side of the die pad section protrudes from the fourth side of the second semiconductor chip.

Claim 4 (Original): A semiconductor device according to claim 3, wherein the first and second semiconductor chips are substantially identical in shape and size.

Claim 5 (Previously Presented): A semiconductor device according to claim 4, wherein a length between the first and second sides of the first semiconductor chip is defined as

a chip length, and a length between the sixth side of the die pad section and the fourth side of the second semiconductor chip is less than or equal to one-fourth the chip length.

Claim 6 (Previously Presented): A semiconductor device according to claim 5, wherein a length between the fourth side of the second semiconductor chip-and the second side of the first semiconductor chip is over 0.1 times half of the chip length and under 0.3 times half of the chip length.

Claim 7 (Previously Presented): A semiconductor device according to claim 6, wherein a thickness of each of the first and second semiconductor chips is over 0.02 times half of the chip length and under 0.06 times half of the chip length.

Claim 8 (Withdrawn): A semiconductor device according to claim 2, wherein the die pad section further includes a through section principally defined in a portion where the first and second semiconductor chips overlap each other.

Claim 9 (Withdrawn): A semiconductor device according to claim 8, wherein the through section is formed only at the portion where the first and second semiconductor chips overlap each other.

Claim 10 (Withdrawn): A semiconductor device according to claim 9, wherein the through section includes either of radial portions, bar-shaped portions, a cross-shaped portion or substantially circular portions.

Claim 11 (Withdrawn): A semiconductor device according to claim 2, wherein the die pad section and the first and second semiconductor chips are substantially rectangular, adjacent two sides of the second semiconductor chip protrude from adjacent two sides of the first semiconductor chip respectively, and adjacent two sides of the die pad section protrude from the adjacent two sides of the first semiconductor chip respectively.

Claim 12 (Withdrawn): A semiconductor device according to claim 2, further comprising:

a third semiconductor chip having a surface on which a third electrode section electrically connected to the lead terminal section is formed, and a back surface fixed to the back surface of the die pad section, and

a fourth semiconductor chip having a surface on which a fourth electrode section electrically connected to the lead terminal section, and a back surface fixed to the surface of the third semiconductor chip,

wherein an edge portion of the fourth semiconductor chip protrudes from an edge portion of the third semiconductor chip and the edge portion of the die pad section protrudes from the edge portion of the third semiconductor chip.

Claim 13 (Withdrawn): A semiconductor device according to claim 2, further comprising a third semiconductor chip fixed to the first semiconductor chip together with the second semiconductor chip.

Claim 14 (Withdrawn): A semiconductor device according to claim 13, wherein an edge portion of the third semiconductor chip protrudes from the edge portion of the first semiconductor chip.

Claim 15 (Canceled)

Claim 16 (Withdrawn): A semiconductor device according to claim 17, wherein the front surface of the die pad section further has a third region that protrudes from the first side, and an amount of protrusion of the third region is larger than an amount of protrusion of the second region.

Claim 17 (Currently Amended): A semiconductor device comprising:

a first semiconductor chip having a first surface, a second surface opposite to the first surface, and a first electrode section formed on said second surface, said second surface having a first side and a second side opposite to the first side;

a second semiconductor chip having a third surface fixed onto the second surface by an adhesive, a fourth surface opposite to the third surface, and a second

electrode section formed on said fourth surface, wherein said fourth surface ~~having~~ has a third side and a fourth side opposite to the third side, and wherein the adhesive is disposed on an entirety of the third surface;

a die pad section having a front surface and a back surface, the first semiconductor chip is fixed to said die pad section at a first region of the front surface, the front surface also including a second region that protrudes from the second side;

lead terminal sections respectively electrically connected to the first and second electrode sections; and

a resin encapsulating body that seals the front and back surfaces of the die pad section, and the first and second semiconductor chips,

wherein the fourth side of the second semiconductor chip protrudes from the second side of the first semiconductor chip, and the second region further protrudes from the fourth side of the second semiconductor chip.

Claim 18 (Original): A semiconductor device according to claim 17, wherein the first and second semiconductor chips are substantially identical in shape and size.

Claim 19 (Previously Presented): A semiconductor device according to claim 18, wherein a length between first and second sides of the first semiconductor chip is defined as a chip length, and a length of the second region which protrudes from the fourth side of the second semiconductor chip, is less than or equal to one-fourth the

chip length.

Claim 20 (Previously Presented): A semiconductor device according to claim 19, wherein length between the fourth side of the second semiconductor chip and the second side of the first semiconductor chip, is over 0.1 times half of the chip length and under 0.3 times half of the chip length.

Claim 21 (Previously Presented): A semiconductor device according to claim 20, wherein a thickness of each of the first and second semiconductor chips is over 0.02 times half of the chip length and under 0.06 times half of the chip length.

Claim 22 (Withdrawn): A semiconductor device according to claim 17, wherein the die pad section further includes a through section principally defined in a portion where the first and second semiconductor chips overlap each other.

Claim 23 (Withdrawn): A semiconductor device according to claim 22, wherein the through section is formed only at the portion where the first and second semiconductor chips overlap each other.

Claim 24 (Withdrawn): A semiconductor device according to claim 23, wherein the through section includes either of radial portions, bar-shaped portions, a cross-shaped

portion or substantially circular portions.

Claim 25 (Withdrawn): A semiconductor device according to claim 17, wherein the second surface of the first semiconductor chip further has a fifth side adjacent to the second side,

the fourth surface of the second semiconductor chip further has a sixth side adjacent to the fourth side,

the die pad section further has a fourth region that protrudes from the fifth side, and

the sixth side of the second semiconductor chip protrudes from the fifth side of the first semiconductor chip.

Claim 26 (Withdrawn): A semiconductor device according to claim 17, further comprising:

a third semiconductor chip having a fifth surface, a sixth surface opposite to the fifth surface, and a third electrode section electrically connected to the lead terminal section formed on the sixth surface, said sixth surface having a seventh side, and

a fourth semiconductor chip having a seventh surface fixed onto the sixth surface, an eighth surface opposite to the seventh surface, and a fourth electrode section electrically connected to the lead terminal section formed on the eighth surface, said eighth surface having an eighth side,

wherein the die pad section further includes, a fifth region on the back surface to which the fifth surface is fixed, and a sixth region on the back surface that protrudes from the seventh side, and

the eighth side of the fourth semiconductor chip protrudes from the seventh side of the third semiconductor chip.

Claim 27 (Withdrawn): A semiconductor device according to claim 17, further comprising a fifth semiconductor chip fixed to the first semiconductor chip together with the second semiconductor chip.

Claim 28 (Withdrawn): A semiconductor device according to claim 27, wherein an edge portion of the fifth semiconductor chip protrudes from the second side of the first semiconductor chip.

Claims 29-30 (Canceled)

Claim 31 (Previously Presented): A semiconductor device according to claim 2, wherein the first and second semiconductor chips are disposed so as to be contained within a perimeter of the surface of the die pad section.

Claim 32 (Previously Presented): A semiconductor device according to claim 17,

wherein the first and second semiconductor chips are disposed so as to be contained within a perimeter of the front surface of the die pad section.